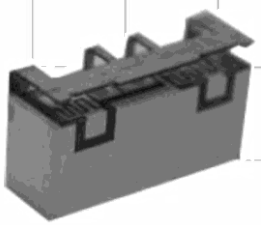
UPB385B - PRELIMINARY

3700-4000MHz UPB Series TDD Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands



Part Dimensions: 10.2 x 5.4 x 4.0 mm • < 1 g
Materials: Ag plated ceramic block with tin plated brass shield

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for 0.25-0.5W at the antenna port.

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	2.0 Watt max
Peak Input Power	-	-	-	20 Watt max
Input-Output Response				
Passband Insertion Loss (5 MHz avg)	3700-4000	1.1 dB	1.4 dB max	1.5 dB max
Passband Ripple	3700-4000	0.7 dB	1.0 dB max	1.0 dB max
Passband Return Loss	3700-4000	14 dB	12 dB min	12 dB min
Attenuation:	1-3400		40 dB min	40 dB min
	4400-5950		40 dB min	40 dB min
	5951-7125		30 dB min	30 dB min
	7126-8000		25 dB min	25 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

Specification Allowance	
Insertion Loss	0.1 dB
Return Loss	1.0 dB
Attenuation	1.0 dB

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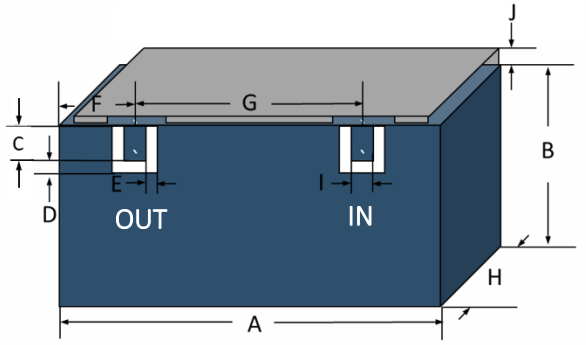
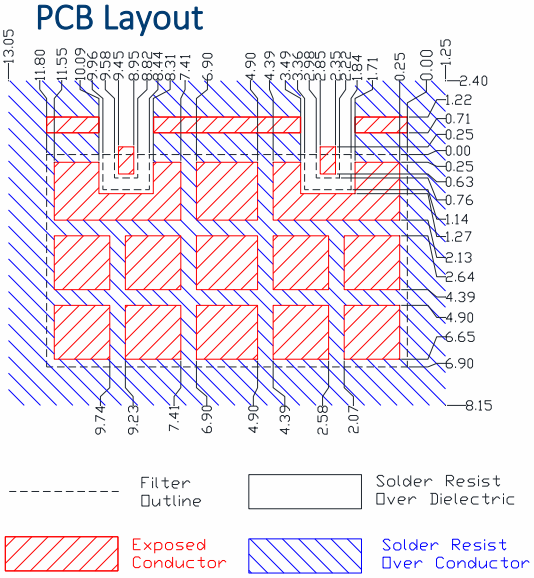
Mechanical Drawing



Dim.	Nominal (mm)	Tolerance (±mm or Max)
A	10.20	0.13
B	4.00	0.30
C	0.76	0.13
D	0.38	0.13
E	0.38	0.13
F	1.80	0.13
G	6.60	0.13
H	3.80	0.30
I	0.76	0.13
J	0.90	0.30

PCB Layout



IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

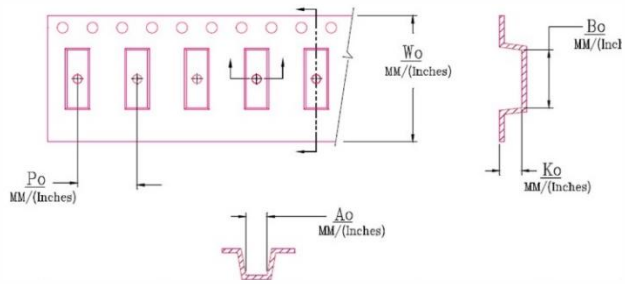
Packaging and Marking

Dimension	Units	Spec.
Reel Diameter	mm	330
Reel Weight	kg	5.5
Reel Quantity	ea.	500

Product Marking

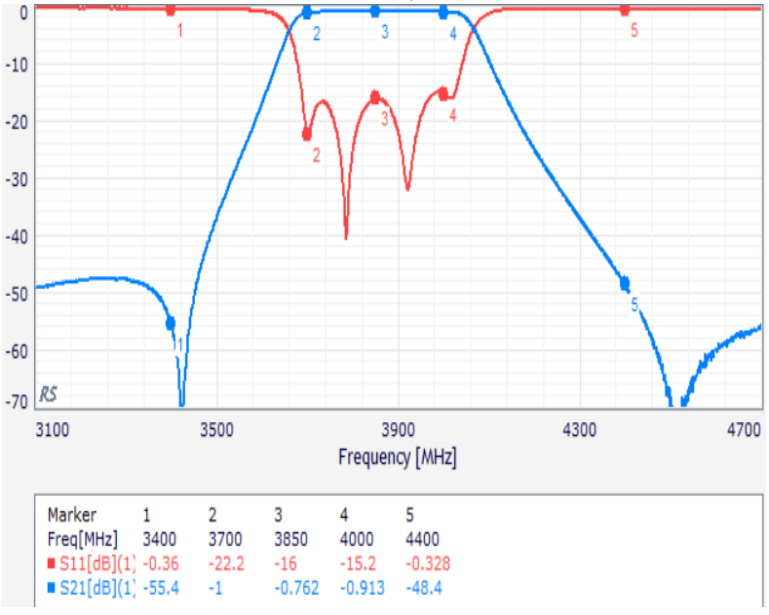
CTS
85B
YWW

Customer Feed Direction → → →



W_o	A_o	B_o	K_o	P_o
0.945 in 24.0 mm	0.319 in 8.10 mm	0.406 in 10.30 mm	0.165 in 4.2 mm	0.472 in 12.0 mm

Electrical Response



Marker	1	2	3	4	5
Freq[MHz]	3400	3700	3850	4000	4400
S11[dB](1)	-0.36	-22.2	-16	-15.2	-0.328
S21[dB](1)	-55.4	-1	-0.762	-0.913	-48.4

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